Author index for papers in Volume 29

Pages are numbered consecutively through the volume: 1–108, January; 109–216, March; 217–328, May; 329–440, July; 441–544, September; and 545–625, November.

Abrams, M., A. Blusson, V. Carrere, T. Nguyen, and Y. Rabu
177 *Image processing applications for geologic mapping*

Akella, Ramakrishna
392 see Gershwin, Stanley B.

Applegate, S., J. Bartlett, A. Bohnhoff, A. Campbell, and J. Molloy
459 *Implementation of the resistive ribbon technology in a printer and correcting typewriter*

Atkinson, J. M., R. D. Granata, H. Leidheiser, Jr., and D. G. McBride
27 *Cathodic delamination of methyl methacrylate-based dry film polymers on copper*

Barojas, Jorge
11 see Chan, Derek Y. C.

Bartlett, J.
459 see Applegate, S.

Bates, R. J. S. and L. A. Sauer
580 *Jitter accommodation in token-passing ring LANs*

Beraud, J. P.
132 see Ungerboeck, G.

Beraud, Jean Paul
140 *Signal processor chip implementation*

Blusson, A.
177 see Abrams, M.

Bogy, D. B.
316 see Bouchard, G.

Bohnhoff, A., D. Croley, S. Dyer, T. Green, R. Maddox, and L. Struttman
494 *System controls for a resistive ribbon printer*

Bohnhoff, A.
459 see Applegate, S.

Borucki, L., H. H. Hansen, and K. Varahramyan
263 *FEDSS—A 2D semiconductor fabrication process simulator*

Bouchard, G., D. B. Bogy, and F. E. Talke
316 *An experimental comparison of the head/disk interface dynamics in 5¼- and 8-inch disk drives*

Brannon, K. W.
229 see O'Brien, R. R.

Brown, James A.
37 *A development of APL2 syntax*

Buturla, Edward M.
277 see Cottrell, Peter E.

Buturla, Edward M.
302 see Farrell, Edward J.

Byrnes, Robert G.
289 see Laux, Steven E.

Campbell, A.
459 see Applegate, S.

Carnevali, P., L. Coletti, and S. Patarnello
569 *Image processing by simulated annealing*

Carrere, V.
177 see Abrams, M.

Chan, Derek Y. C., Douglas Henderson, Jorge Barojas, and Andrew M. Homola
11 *The stability of a colloidal suspension of coated magnetic particles in an aqueous solution*

Chang, F.-Y. and L. F. Wagner
252 *The generation of three-dimensional bipolar transistor models for circuit analysis*

Chang, F.-Y.
218 see Knepper, R. W.

Chevillat, P. R.
132 see Ungerboeck, G.

Chieu, T. C. and O. Sahni
509 *Ink temperatures in resistive ribbon thermal transfer printing*

Choong, Yong F.
392 see Gershwin, Stanley B.

Chow, We-Min, Edward A. MacNair, and Charles H. Sauer
330 *Analysis of manufacturing systems by the Research Queueing Package*

Cobb, R. H.
478 see DeFosse, S. F.

Coletti, L.
569 see Carnevali, P.

Cook, R. K.
242 see Gaur, S. P.

Corongiu, G. and J. H. Detrich
422 *Large-scale scientific application programs in chemistry and physics on an experimental parallel computer system*

Corson, Phillip L.
302 see Farrell, Edward J.

Cottrell, Peter E. and Edward M. Buturla
277 *VLSI wiring capacitance*

Couturier, C.
147 see Galand, C.

Croley, D.
494 see Bohnhoff, A.

Crooks, Walter
449 see Pennington, Keith S.

DeFosse, S. F., G. T. Williams, D. A. Gostomski, Jr., and R. H. Cobb
478 *Development of a membrane switch-type full-travel tactile keyboard*

Detrich, J. H.
422 see Corongiu, G.

Dove, D. B.
519 see Shih, K. K.

Dyer, S.
494 see Bohnhoff, A.

Engelke, H., J. Grotrian, C. Scheuing, A. Schmackpfeffer, W. Schwarz, B. Solf, and J. Tomann
343 *Integrated Manufacturing Modeling System*

Farrell, Edward J., Steven E. Laux, Phillip L. Corson, and Edward M. Buturla
302 *Animation and 3D color display of multiple-variable data: Application to semiconductor design*

Fellenstein, Craig, Charles O. Green, Lucinda M. Palmer, Adrian Walker, and David J. Wyler
413 *A prototype manufacturing knowledge base in Syllog*

Galand, C., C. Couturier, G. Platel, and R. Vermot-Gauchy
147 *Voice-excited predictive coder (VEPC) implementation on a high-performance signal processor*

Gaur, S. P., P. A. Habitz, Y.-J. Park, R. K. Cook, Y.-S. Huang, and L. F. Wagner
242 *Two-dimensional device simulation program: 2DP*

Gaur, S. P.
218 see Knepper, R. W.

Gershwin, Stanley B., Ramakrishna Akella, and Yong F. Choong
392 *Short-term production scheduling of an automated manufacturing facility*

Gostomski, D. A., Jr.
478 see DeFosse, S. F.

Granata, R. D.
27 see Atkinson, J. M.

Green, Charles O.
413 see Fellenstein, Craig

Green, T.
494 see Bohnhoff, A.

Grotrian, J.
343 see Engelke, H.

Haas, Peter J. and Gerald S. Shedler
194 *Regenerative simulation methods for local area computer networks*

Habitz, P. A.
242 see Gaur, S. P.

Haines, C. L.
356 *An algorithm for carrier routing in a flexible material-handling system*

Hansen, H. H.
263 see Borucki, L.

Henderson, Douglas
11 see Chan, Derek Y. C.

Hollis, Ralph L.
363 see Taylor, Russell H.

Homola, Andrew M.
11 see Chan, Derek Y. C.

Hsieh, C. M.
229 see O'Brien, R. R.

Huang, Y.-S.
242 see Gaur, S. P.

Kaeser, H.-P.
132 see Ungerboeck, G.

Knepper, R. W., S. P. Gaur, F.-Y. Chang, and G. R. Srinivasan
218 *Advanced bipolar transistor modeling: Process and device simulation tools for today's technology*

Knepper, R. W.
229 see O'Brien, R. R.

Kotkiewicz, S. M.
18 see Marsh, L. L.

Laff, Robert A. and Claus D. Makowka
527 *Thermal behavior of resistive ribbon for single-stylus excitation*

Langdon, Glen G., Jr.
188 see Todd, Stephen

Langlois, W. E.
2 *The dynamical equations governing a lubricating film consisting of a gas film overlying a liquid film*

Laux, Steven E. and Robert G. Byrnes
289 *Semiconductor device simulation using generalized mobility models*

Laux, Steven E.
302 see Farrell, Edward J.

Lavin, Mark A.
363 see Taylor, Russell H.

Leidheiser, H., Jr.
27 see Atkinson, J. M.

Lever, R. F.
229 see O'Brien, R. R.

MacNair, Edward A.
330 see Chow, We-Min

Maddox, R.
494 see Bohnhoff, A.

Maiwald, D.
132 see Ungerboeck, G.

Makowka, Claus D.
527 see Laff, Robert A.

Mandeville, Jon R.
73 *Novel method for analysis of printed circuit images*

Marsh, L. L., D. C. Van Hart, and S. M. Kotkiewicz
18 *A dielectric loss investigation of moisture in epoxy-glass composites*

Matino, Haruhiro
588 *Analysis of the holding current in CMOS latch-up*

Mayo, R. D.
488 *System control for a printwheel typewriter*

McBride, D. G.
27 see Atkinson, J. M.

Molloy, J.
459 see Applegate, S.

Moore, J. S.
229 see O'Brien, R. R.

Murley, P. C.
229 see O'Brien, R. R.

Nguyen, T.
177 see Abrams, M.

O'Brien, R. R., C. M. Hsieh, J. S. Moore, R. F. Lever, P. C. Murley, K. W. Brannon, G. R. Srinivasan, and R. W. Knepper
229 *Two-dimensional process modeling: A description of the SAFEPRO program*

O'Malley, Lawrence V.
68 *Adaptive clustering algorithm*

Palmer, Lucinda M.
413 see Fellenstein, Craig

Park, Y.-J.
242 see Gaur, S. P.

Patarnello, S.
569 see Carnevali, P.

Patel, Arvind M.
546 *Adaptive cross-parity (AXP) code for a high-density magnetic tape subsystem*

Pennington, Keith S. and Walter Crooks
449 *Resistive ribbon thermal transfer printing: A historical review and introduction to a new printing technology*

Platel, G.
147 see Galand, C.

Rabu, Y.
177 see Abrams, M.

Rayfield, James T. and Harvey F. Silverman
170 *An approach to DFT calculations using standard microprocessors*

Rissanen, Jorma
188 see Todd, Stephen

Sahni, O.
509 see Chieu, T. C.

Sauer, Charles H.
330 see Chow, We-Min

Sauer, L. A.
580 see Bates, R. J. S.

Scheuing, C.
343 see Engelke, H.

Schmackpfeffer, A.
343 see Engelke, H.

Schneider, Richard C.
563 *Write equalization in high-linear-density magnetic recording*

Schwarz, B.
343 see Engelke, H.

Shedler, Gerald S.
194 see Haas, Peter J.

Schichman, G.
158 *Personal Instrument (PI)—A PC-based signal processing system*

Shih, K. K. and D. B. Dove
519 *Electrical properties of resistive ribbon*

Silverman, Harvey F.
170 see Rayfield, James T.

Solf, B.
343 see Engelke, H.

Srinivasan, G. R.
218 see Knepper, R. W.

Srinivasan, G. R.
229 see O'Brien, R. R.

Stanley, Robert C.
110 *Microprocessors in brief*

Stapper, C. H.
87 *The effects of wafer to wafer defect density variations on integrated circuit defect and fault distributions*

Struttmann, L.
494 see Bohnhoff, A.

Takagi, N. and C. K. Wong
49 *A hardware sort-merge system*

Talke, F. E.
316 see Bouchard, G.

Taylor, Russell H., Ralph L. Hollis, and Mark A. Lavin
363 *Precise manipulation with endpoint sensing*

Todd, Stephen, Glen G. Langdon, Jr., and Jorma Rissanen
188 *Parameter reduction and context selection for compression of gray-scale images*

Tomann, J.
343 see Engelke, H.

Twardeck, T. G.
470 *Characterization of a resistive ribbon thermal transfer printing process*

Ungerboeck, G., D. Maiwald, H.-P. Kaeser, P. R. Chevillat, and J. P. Beraud
132 *Architecture of a digital signal processor*

Van Hart, D. C.
18 see Marsh, L. L.

Varahramyan, K.
263 see Borucki, L.

Vermot-Gauchy, R.
147 see Galand, C.

Wagner, L. F.
252 see Chang, F.-Y.

Wagner, L. F.
242 see Gaur, S. P.

Walker, Adrian
413 see Fellenstein, Craig

Williams, G. T.
478 see DeFosse, S. F.

Williams, T. H.
443 *Design and implementation of the ®SELECTRIC System/2000*

Wittrock, Robert J.
401 *Scheduling algorithms for flexible flow lines*

Wong, C. K.
49 see Takagi, N.

Wyler, David J.
413 see Fellenstein, Craig

Yashchin, Emmanuel
377 *On the analysis and design of CUSUM-Shewhart control schemes*

Subject index for papers in Volume 29

Each index entry below is accompanied by an author's name and a page number; the author index contains the title of the paper and the names of coauthors, if any. Communications are identified by (C).

Subject	*Author*	*Page*
Algorithms		
Adaptive clustering algorithm	O'Malley	68
Algorithm for carrier routing in a flexible material-handling system	Haines	356
Approach to DFT calculations using standard microprocessors	Rayfield	170
Hardware sort-merge system	Takagi	49
Image processing by simulated annealing	Carnevali	569
Novel method for analysis of printed circuit images	Mandeville	73
Prototype manufacturing knowledge base in Syllog	Fellenstein	413
Scheduling algorithms for flexible flow lines	Wittrock	401
Short-term production scheduling of an automated manufacturing facility	Gershwin	392
Analytical models		
Image processing by simulated annealing	Carnevali	569
Channel subsystem architecture		
Write equalization in high-linear-density magnetic recording	Schneider	563
Coding theory		
Adaptive cross-parity (AXP) code for a high-density magnetic tape subsystem	Patel	546
Communications and communication networks		
Jitter accommodation in token-passing ring LANs	Bates	580
Compilers and interpreters		
Development of *APL2* syntax	Brown	37
Computational methods		
Approach to DFT calculations using standard microprocessors	Rayfield	170
Large-scale scientific application programs in chemistry and physics on an experimental parallel computer system	Corongiu	422
Computer applications		
Large-scale scientific application programs in chemistry and physics on an experimental parallel computer system	Corongiu	422
Computer architecture		
Hardware sort-merge system	Takagi	49
Computer-controlled manipulators		
Precise manipulation with endpoint sensing	Taylor	363
Computer organization and design		
Large-scale scientific application programs in chemistry and physics on an experimental parallel computer system	Corongiu	422
Computer performance analysis		
Large-scale scientific application programs in chemistry and physics on an experimental parallel computer system	Corongiu	422
Control systems		
Precise manipulation with endpoint sensing	Taylor	363
Disk files		
Experimental comparison of the head/disk interface dynamics in 5¼- and 8-inch disk drives	Bouchard	316
Display technology		
Animation and 3D color display of multiple-variable data: Application to semiconductor design	Farrell	302
Electrical packaging technology		

Cathodic delamination of methyl methacrylate-based dry film polymers on copper — Atkinson 27
Dielectric loss investigation of moisture in epoxy-glass composites — Marsh 18

Error detection and correction
Adaptive cross-parity (AXP) code for a high-density magnetic tape subsystem — Patel 546

Graphics
Animation and 3D color display of multiple-variable data: Application to semiconductor design — Farrell 302

Image processing
Image processing applications for geologic mapping — Abrams 177
Image processing by simulated annealing — Carnevali 569
Novel method for analysis of printed circuit images — Mandeville 73
Parameter reduction and context selection for compression of gray-scale images — Todd 188

Impact printer technology
Design and implementation of the ®SELECTRIC System/2000 — Williams 443
System control for a printwheel typewriter — Mayo 488

I/O devices
Experimental comparison of the head/disk interface dynamics in 5¼- and 8-inch disk drives — Bouchard 316

Keyboard design
Development of a membrane switch-type full-travel tactile keyboard — DeFosse 478

Large-scale computing
Large-scale scientific application programs in chemistry and physics on an experimental parallel computer system — Corongiu 422

Large-scale integration
Architecture of a digital signal processor — Ungerboeck 132
Effects of wafer to wafer defect density variations on integrated circuit defect and fault distributions — Stapper 87
Microprocessors in brief — Stanley 110
Signal processor chip implementation — Beraud 140

Local area networks
Jitter accommodation in token-passing ring LANs — Bates 580
Regenerative simulation methods for local area computer networks — Haas 194

Logic design and technology
Architecture of a digital signal processor — Ungerboeck 132
Microprocessors in brief — Stanley 110
Signal processor chip implementation — Beraud 140

LSI design automation
Advanced bipolar transistor modeling: Process and device simulation tools for today's technology — Knepper 218
Animation and 3D color display of multiple-variable data: Application to semiconductor design — Farrell 302
FEDSS—A 2D semiconductor fabrication process simulator — Borucki 263
Generation of three-dimensional bipolar transistor models for circuit analysis — Chang 252
Semiconductor device simulation using generalized mobility models — Laux 289
Two-dimensional device simulation program: 2DP — Gaur 242
Two-dimensional process modeling: A description of the SAFEPRO program — O'Brien 229
VLSI wiring capacitance — Cottrell 277

Lubrication
Dynamical equations governing a lubricating film consisting of a gas film overlying a liquid film — Langlois 2

Magnetic head/disk interaction
Experimental comparison of the head/disk interface dynamics in 5¼- and 8-inch disk drives — Bouchard 316

Magnetic recording
Adaptive cross-parity (AXP) code for a high-density magnetic tape subsystem — Patel 546
Write equalization in high-linear-density magnetic recording — Schneider 563

Manufacturing technology
Advanced bipolar transistor modeling: Process and device simulation tools for today's technology — Knepper 218
Algorithm for carrier routing in a flexible material-handling system — Haines 356
Analysis and design of CUSUM-Shewhart control schemes — Yashchin 377
Analysis of manufacturing systems by the Research Queueing Package — Chow 330
Animation and 3D color display of multiple-variable data: Application to semiconductor design — Farrell 302
Effects of wafer to wafer defect density variations on integrated circuit defect and fault distributions — Stapper 87
FEDSS—A 2D semiconductor fabrication process simulator — Borucki 263
Generation of three-dimensional bipolar transistor models for circuit analysis — Chang 252
Integrated Manufacturing Modeling System — Engelke 343
Prototype manufacturing knowledge base in Syllog — Fellenstein 413
Scheduling algorithms for flexible flow lines — Wittrock 401
Semiconductor device simulation using generalized mobility models — Laux 289
Short-term production scheduling of an automated manufacturing facility — Gershwin 392
Two-dimensional device simulation program: 2DP — Gaur 242
Two-dimensional process modeling: A description of the SAFEPRO program — O'Brien 229
VLSI wiring capacitance — Cottrell 277

Materials
Cathodic delamination of methyl methacrylate-based dry film polymers on copper — Atkinson 27
Dielectric loss investigation of moisture in epoxy-glass composites — Marsh 18
Electrical properties of resistive ribbon — Shih 519
Implementation of the resistive ribbon technology in a printer and correcting typewriter — Applegate 459

Ink temperatures in resistive ribbon thermal transfer printing — Chieu — 509
Resistive ribbon thermal transfer printing: A historical review and introduction to a new printing technology — Pennington — 449
Stability of a colloidal suspension of coated magnetic particles in an aqueous solution — Chan — 11
Thermal behavior of resistive ribbon for single-stylus excitation — Laff — 527

Mathematics (applied)
Large-scale scientific application programs in chemistry and physics on an experimental parallel computer system — Corongiu — 422

Mechanics and mechanisms
Precise manipulation with endpoint sensing — Taylor — 363
System control for a printwheel typewriter — Mayo — 488
System controls for a resistive ribbon printer — Bohnhoff — 494

Microprocessor-based applications
Approach to DFT calculations using standard microprocessors — Rayfield — 170
Personal Instrument (PI)—A PC-based signal processing system — Shichman — 158
Voice-excited predictive coder (VEPC) implementation on a high-performance signal processor — Galand — 147

Microprocessors
Architecture of a digital signal processor — Ungerboeck — 132
Microprocessors in brief — Stanley — 110

Modeling and modeling
Advanced bipolar transistor modeling: Process and device simulation tools for today's technology — Knepper — 218
Animation and 3D color display of multiple-variable data: Application to semiconductor design — Farrell — 302
Dynamical equations governing a lubricating film consisting of a gas film overlying a liquid film — Langlois — 2
FEDSS—A 2D semiconductor fabrication process simulator — Borucki — 263
Generation of three-dimensional bipolar transistor models for circuit analysis — Chang — 252
Regenerative simulation methods for local area computer networks — Haas — 194
Semiconductor device simulation using generalized mobility models — Laux — 289
Stability of a colloidal suspension of coated magnetic particles in an aqueous solution — Chan — 11
Two-dimensional device simulation program: 2DP — Gaur — 242
Two-dimensional process modeling: A description of the SAFEPRO program — O'Brien — 229
VLSI wiring capacitance — Cottrell — 277

Parallel processing
Large-scale scientific application programs in chemistry and physics on an experimental parallel computer system — Corongiu — 422

Personal computer applications
Personal Instrument (PI)—A PC-based signal processing system — Shichman — 158

Physics and physical chemistry
Cathodic delamination of methyl methacrylate-based dry film polymers on copper — Atkinson — 27
Dielectric loss investigation of moisture in epoxy-glass composites — Marsh — 18
Large-scale scientific application programs in chemistry and physics on an experimental parallel computer system — Corongiu — 422
Stability of a colloidal suspension of coated magnetic particles in an aqueous solution — Chan — 11

Plant automation
Algorithm for carrier routing in a flexible material-handling system — Haines — 356
Analysis and design of CUSUM-Shewhart control schemes — Yashchin — 377
Analysis of manufacturing systems by the Research Queueing Package — Chow — 330
Integrated Manufacturing Modeling System — Engelke — 343
Prototype manufacturing knowledge base in Syllog — Fellenstein — 413
Scheduling algorithms for flexible flow lines — Wittrock — 401
Short-term production scheduling of an automated manufacturing facility — Gershwin — 392

Printing technology
Characterization of a resistive ribbon thermal transfer printing process — Twardeck — 470
Design and implementation of the *SELECTRIC System/2000 — Williams — 443
Development of a membrane switch-type full-travel tactile keyboard — DeFosse — 478
Electrical properties of resistive ribbon — Shih — 519
Implementation of the resistive ribbon technology in a printer and correcting typewriter — Applegate — 459
Ink temperatures in resistive ribbon thermal transfer printing — Chieu — 509
Resistive ribbon thermal transfer printing: A historical review and introduction to a new printing technology — Pennington — 449
System control for a printwheel typewriter — Mayo — 488
System controls for a resistive ribbon printer — Bohnhoff — 494
Thermal behavior of resistive ribbon for single-stylus excitation — Laff — 527

Programming and programming languages
Development of *APL2* syntax — Brown — 37

Quality control
Effects of wafer to wafer defect density variations on integrated circuit defect and fault distributions — Stapper — 87
Experimental comparison of the head/disk interface dynamics in 5¼- and 8-inch disk drives — Bouchard — 316
Novel method for analysis of printed circuit images — Mandeville — 73

Queueing theory
Analysis of manufacturing systems by the Research Queueing Package — Chow — 330

Relational databases
Prototype manufacturing knowledge base in Syllog — Fellenstein 413

Scheduling
Algorithm for carrier routing in a flexible material-handling system — Haines 356
Analysis and design of CUSUM-Shewhart control schemes — Yashchin 377
Analysis of manufacturing systems by the Research Queueing Package — Chow 330
Prototype manufacturing knowledge base in Syllog — Fellenstein 413
Scheduling algorithms for flexible flow lines — Wittrock 401
Short-term production scheduling of an automated manufacturing facility — Gershwin 392

Semiconductor device analysis
Analysis of the holding current in CMOS latch-up (C) — Matino 588

Semiconductor technology
Advanced bipolar transistor modeling: Process and device simulation tools for today's technology — Knepper 218
Animation and 3D color display of multiple-variable data: Application to semiconductor design — Farrell 302
Effects of wafer to wafer defect density variations on integrated circuit defect and fault distributions — Stapper 87
Experimental comparison of the head/disk interface dynamics in 5¼- and 8-inch disk drives — Bouchard 316
FEDSS—A 2D semiconductor fabrication process simulator — Borucki 263
Generation of three-dimensional bipolar transistor models for circuit analysis — Chang 252
Semiconductor device simulation using generalized mobility models — Laux 289
Two-dimensional device simulation program: 2DP — Gaur 242
Two-dimensional process modeling: A description of the SAFEPRO program — O'Brien 229
VLSI wiring capacitance — Cottrell 277

Signal processing
Adaptive clustering algorithm — O'Malley 68
Architecture of a digital signal processor — Ungerboeck 132
Personal Instrument (PI)—A PC-based signal processing system — Shichman 158
Signal processor chip implementation — Beraud 140
Voice-excited predictive coder (VEPC) implementation on a high-performance signal processor — Galand 147
Write equalization in high-linear-density magnetic recording — Schneider 563

Simulation
Integrated Manufacturing Modeling System — Engelke 343
Regenerative simulation methods for local area computer networks — Haas 194

Sorting
Adaptive clustering algorithm — O'Malley 68
Hardware sort-merge system — Takagi 49

Speech processing
Personal Instrument (PI)—A PC-based signal processing system — Shichman 158
Voice-excited predictive coder (VEPC) implementation on a high-performance signal processor — Galand 147

Statistics
Effects of wafer to wafer defect density variations on integrated circuit defect and fault distributions — Stapper 87

System architecture
Large-scale scientific application programs in chemistry and physics on an experimental parallel computer system — Corongiu 422

System architecture and development
Large-scale scientific application programs in chemistry and physics on an experimental parallel computer system — Corongiu 422

Thermal transfer printing
Characterization of a resistive ribbon thermal transfer printing process — Twardeck 470
Design and implementation of the *SELECTRIC System/2000 — Williams 443
Electrical properties of resistive ribbon — Shih 519
Implementation of the resistive ribbon technology in a printer and correcting typewriter — Applegate 459
Ink temperatures in resistive ribbon thermal transfer printing — Chieu 509
Resistive ribbon thermal transfer printing: A historical review and introduction to a new printing technology — Pennington 449
Thermal behavior of resistive ribbon for single-stylus excitation — Laff 527

Token-passing rings
Jitter accommodation in token-passing ring LANs — Bates 580

Typewriter design
Characterization of a resistive ribbon thermal transfer printing process — Twardeck 470
Design and implementation of the *SELECTRIC System/2000 — Williams 443
Development of a membrane switch-type full-travel tactile keyboard — DeFosse 478
Electrical properties of resistive ribbon — Shih 519
Implementation of the resistive ribbon technology in a printer and correcting typewriter — Applegate 459
Ink temperatures in resistive ribbon thermal transfer printing — Chieu 509
Resistive ribbon thermal transer printing: A historical review and introduction to a new printing technology — Pennington 449
System control for a printwheel typewriter — Mayo 488
System controls for a resistive ribbon printer — Bohnhoff 494
Thermal behavior of resistive ribbon for single-stylus excitation — Laff 527